



SOT983-1

DFN1714U-8: plastic thermal enhanced extremely thin small outline package; no leads; 8 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN1714U-8
Package type industry code	DFN1714U-8
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package style suffix code	U (UTLP based)
Package body material type	P (plastic)
IEC package outline code	- - -
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	14-11-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.65	-	1.7	1.75	mm
E	package width	1.3	-	1.35	1.4	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	8	-	



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2. Package outline

HXSON8U: plastic thermal enhanced extremely thin small outline package; no leads; 8 terminals; UTLP based; body 1.35 x 1.7 x 0.5 mm

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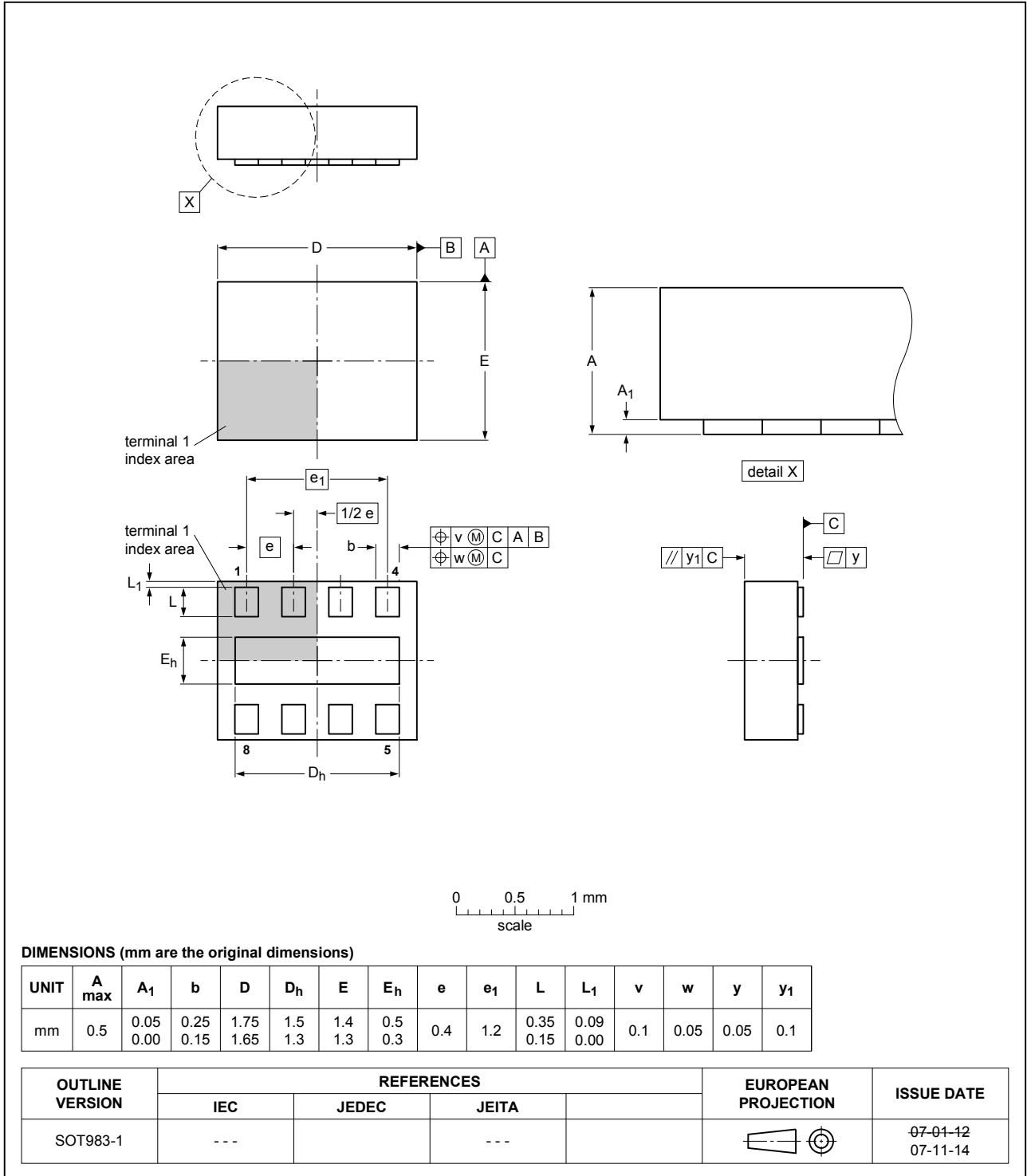


Fig. 1. Package outline DFN1714U-8 (SOT983-1)

3. Soldering

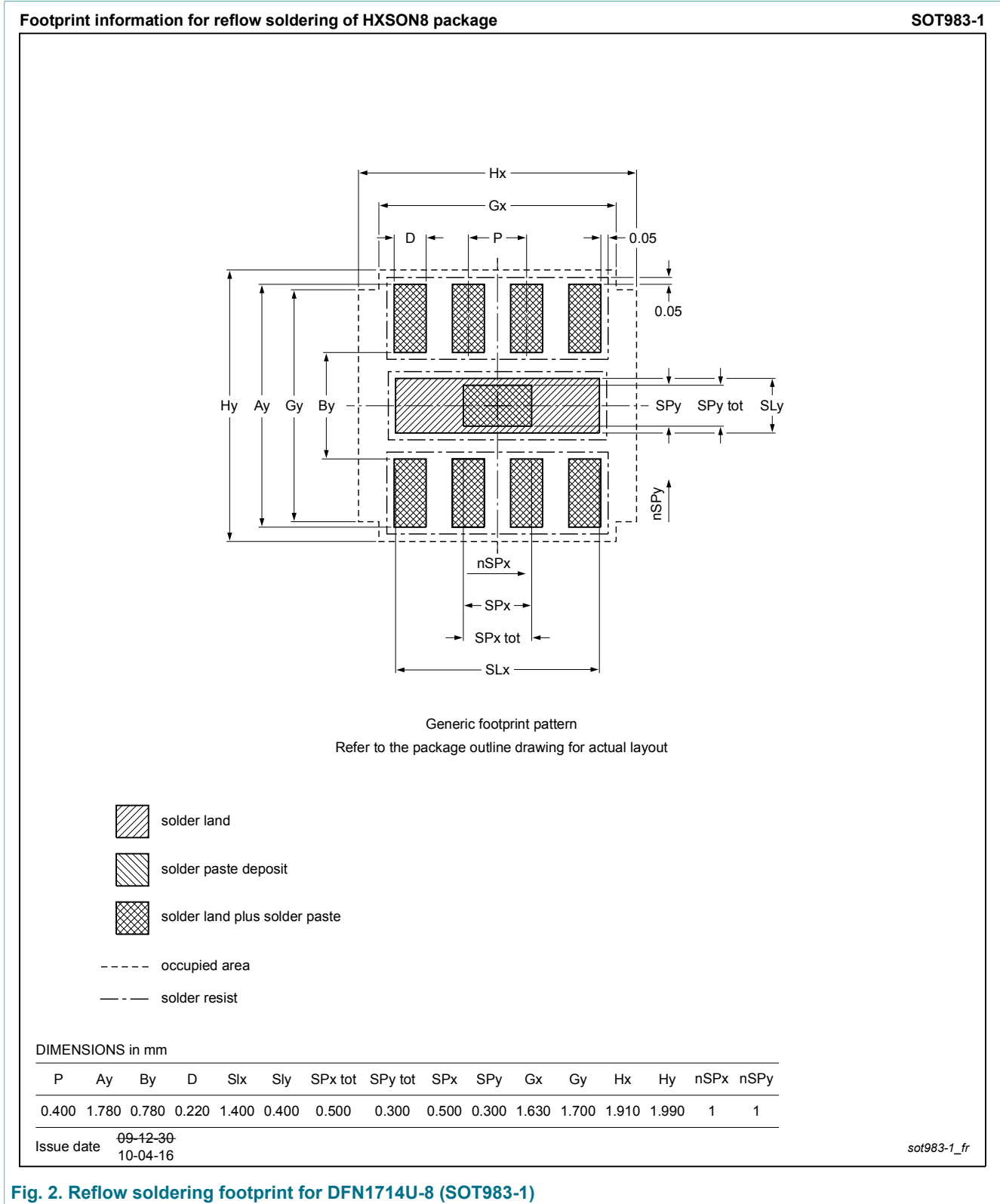


Fig. 2. Reflow soldering footprint for DFN1714U-8 (SOT983-1)

4. Legal information

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Date of release: 8 February 2016
